

Interfacial reactions between lead-free solders and com

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Citation Report

#	ARTICLE	IF	CITATIONS
1	Degradation Mechanism on Joint of Between Ag-Epoxy Conductive Adhesive and Sn/Ni Plating Chip by Reliability Test. Journal of the Adhesion Society of Japan, 2005, 41, 490-497.	0.0	0
2	Effects of Cu Contents in Sn-Cu Solder on the Composition and Morphology of Intermetallic Compounds at a Solder/Ni Interface. Journal of Materials Research, 2005, 20, 2205-2212.	1.2	44
3	IMC Evolution and Reliability of Lead-free Solder Bump Formed by Induction Self Heat Reflow. , 0, , .		1
4	Interfacial reactions between Pb-free solders and metallized substrate surfaces. , 0, , .		1
5	Interfacial Reaction and Joint Reliability of Sn-Ag-Cu/OSP-Cu Pad SMT Solder Joint. , 2006, , .		3
6	Effect of Ni on the Formation of Cu ₆ Sn ₅ and Cu ₃ Sn Intermetallics. , 0, , .		12
7	Effect of Solder Volume on Interfacial Reactions between Eutectic Sn-Pb and Sn-Ag-Cu Solders and Ni(P)-Au Surface Finish. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2006, , .	0.0	4
8	Ag-Sn Fluxless Wafer Bonding Technology. , 2006, , .		2
9	Electromigration of 96.5Sn-3Ag-0.5Cu Flip-chip Solder Bumps Bonded on Substrate Pads of Au/Ni/Cu or Cu Metallization. , 0, , .		8
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